■ MN101C47 Series

Туре	MN101C47C	MN101C47D	MN101CF46F
Internal ROM type	Mask ROM		FLASH
ROM (byte)	48K	64K	96K
RAM (byte)	1.5K	2K	3K
Package (Lead-free)	LQFF004-F-1414, SDFF042-F-0000C		LQFP064-P-1414 (ES (Engineering Sample) available), SDIP042-P-0600C (ES (Engineering Sample) available)
Minimum Instruction Execution Time	279 ns (3.0 V to 3.6 V, 14.32 MHz)		

■ Interrupts

External (6 lines)

 $Internal~(8~lines): Timer \times 3, A/D, OSD, I^2C, Remote~control,~Watchdog$

■ Timer Counter

8-bit timer \times 3

Watchdog timer: system clock fs 1/216, 1/218, 1/220 triple selection

■ Serial interface

 $I^2C \times 1$: for multimaster mode, bus line (output) has 2 systems

■ Caption / Teletext Decoder

Built-in sync separator × 2

■ I/O Pins

I/O 35 : Common use : 29

■ A/D converter

5-bit \times 8-ch. (with S/H)

■ PWM

8-bit \times 6-ch., 14-bit \times 1-ch.

■ Special Ports

Remote control reception

■ CRTC

1-layer display (graphics, characters)

■ Notes

Remote control input discriminant circuit built-in

■ Development tools

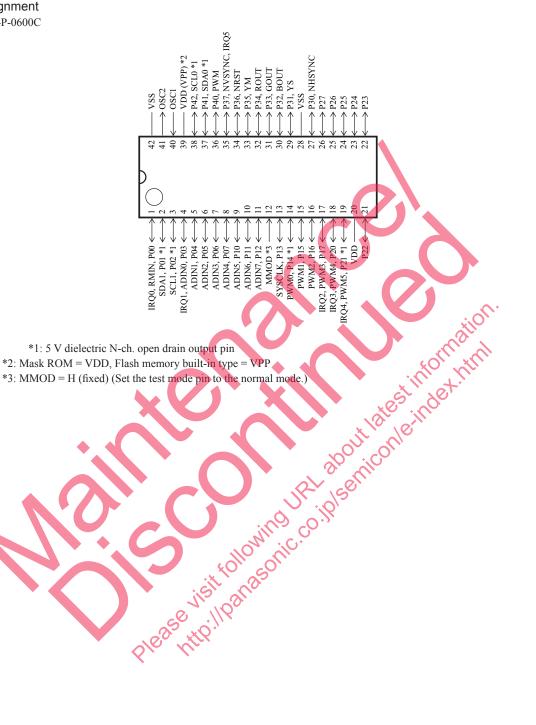
In-circuit Emulator

PX-ICE101C/D + PX-PRB101C46-SDP042-P-0600-M (Under development)

Panasonic MAD00027EEM

■ Pin Assignment SDIP042-P-0600C

Note)



MAD00027EEM Panasonic

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- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the clapsed time since first opening the packages.
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